

Reg No.: _____

Name: _____

APJ ABDUL KALAM TECHNOLOGICAL UNIVERSITY

Seventh semester B.Tech examinations (S), September 2020

Course Code: EC465**Course Name: MEMS**

Max. Marks: 100

Duration: 3 Hours

PART A*Answer any two full questions, each carries 15 marks.*

Marks

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|---|--|-----|
| 1 | a) Explain different types of micro-accelerometers with diagrams. | (7) |
| | b) Explain the principle of operation of MEMS based electrostatic sensors and actuators. | (8) |
| 2 | a) Derive the expression for longitudinal strain under pure bending in flexural beams | (8) |
| | b) Explain the general stress -strain relationship with neat sketches | (7) |
| 3 | a) Explain the working principle of micro-grippers and micro pumps | (8) |
| | b) Explain the operating principle of thermal bimorphs with figures.State any two applications of thermal sensors. | (7) |

PART B*Answer any two full questions, each carries 15 marks.*

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| 4 | a) With reference to scaling of electrostatic forces, derive the expressions for electrostatic potential energy and force | (8) |
| | b) Compare the properties of Silicon, SiO ₂ and SiC | (7) |
| 5 | a) Compare different chemical vapour deposition processes. | (8) |
| | b) Explain various scaling laws in miniaturization. | (7) |
| 6 | a) Derive equations for acceleration a, time t and power density P/V based on the Trimmer Force Scaling Vector. What inference can a MEMS designer draw from the force scaling vector? | (8) |
| | b) Explain two processes used for doping silicon substrate and also specify two n and p type dopants. | (7) |

PART C

Answer any two full questions, each carries 20 marks.

- 7 a) Explain with figures the steps in surface micromachining. Discuss the various fabrication challenges associated with surface micromachining. (10)
- b) Explain the levels of micro system packaging. (10)
- 8 a) Explain any two bonding techniques for MEMS (10)
- b) Explain with diagrams any two applications of RFMEMS. (10)
- 9 a) Describe steps of fabrication of a square tube using LIGA process. (10)
- b) Explain two applications which use NEMS technology. (10)
